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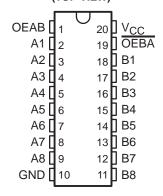
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (N) and Ceramic (JT) DIPs

description

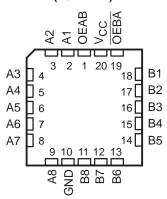
The SN54ABT623A and SN74ABT623 bus transceivers are designed for asynchronous communication between data buses. The control-function implementation allows for maximum flexibility in timing. The SN54ABT623A and SN74ABT623 provide true data at their outputs.

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB and OEBA) inputs.

SN54ABT623A . . . JT OR W PACKAGE SN74ABT623 . . . DB, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABT623A . . . FK PACKAGE (TOP VIEW)



The output-enable inputs can be used to disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability of storing data by simultaneously enabling OEAB and OEBA. Each output reinforces its input in this configuration. When both OEAB and OEBA are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (16 total) remain at their last states.

To ensure the high-impedance state during power up or power down, $\overline{\text{OEBA}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT623A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT623 is characterized for operation from –40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

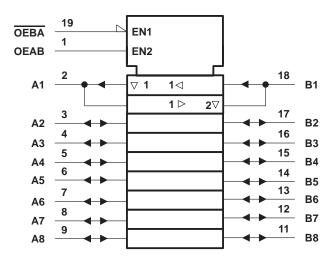
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FUNCTION TABLE

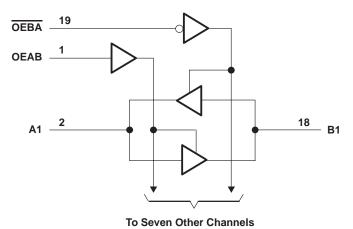
INP	JTS	OPERATION					
OEBA	OEAB						
L	L	B data to A bus					
L	Н	B data to A bus, A data to B bus					
Н	L	Isolation					
Н	Н	A data to B bus					

logic symbol†



 $^{^\}dagger$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see N		
Voltage range applied to any output in the high	or power-off state, V _O	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN	I54ABT623A	96 mA
SN	I74ABT623	128 mA
Input clamp current, I _{IK} (V _I < 0)		–18 mA
Output clamp current, I _{OK} (V _O < 0)		–50 mA
Package thermal impedance, θ _{JA} (see Note 2):	: DB package	115°C/W
•	DW package	97°C/W
	N package	67°C/W
	PW package	128°C/W
Storage temperature range, T _{stg}		. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

				T623A	SN74ABT623		UNIT
			MIN	MAX	MIN	MAX	UNII
V _{CC} Supply voltage				5.5	4.5	5.5	V
V _{IH} High-level input voltage					2		V
V _{IL} Low-level input voltage				0.8		0.8	V
V _I Input voltage			0	VCC	0	VCC	V
IOH High-level output current				-24		-32	mA
IOL Low-level output current				48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
TA	T _A Operating free-air temperature			125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.



SN54ABT623A, **SN74ABT623 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS**

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A = 25°C			SN54ABT623A		SN74ABT623		UNIT	
				MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNII	
٧ıK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\/a		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
VOH		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				V	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
VOL		V00 - 45 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL	V _{CC} = 4.5 V		I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100						mV	
١,	Control inputs	V00 = 5.5.V	VI = VCC or GND			±1		±1		±1	μА	
ΙΙ	A or B ports	V _C C = 5.5 V,	1 = 100 01 014D			±100		±100		±100	μΛ	
lozh‡		$V_{CC} = 5.5 V$,	$V_0 = 2.7 \text{ V}$			50**		10		50	μΑ	
lozL [‡]		$V_{CC} = 5.5 V$,	$V_0 = 0.5 V$			-50**		-10		-50	μΑ	
I _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ	
I _O §		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
			Outputs high		5	250		250		250	μΑ	
ICC	A or B ports		Outputs low		22	30		30		30	mA	
			$V_I = V_{CC}$ or GND	Outputs disabled		1	250		250		250	μΑ
	Data inputs Control inputs	innut at	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5	
ΔICC¶		Other inputs at V _{CC} or GND	Outputs disabled			0.05		0.05		0.05	mA	
		V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1.5		1.5		1.5		
Ci	Control inputs	V _I = 2.5 V or 0.5 V			4						pF	
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			7						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



^{**} These limits apply only to the SN74ABT623.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

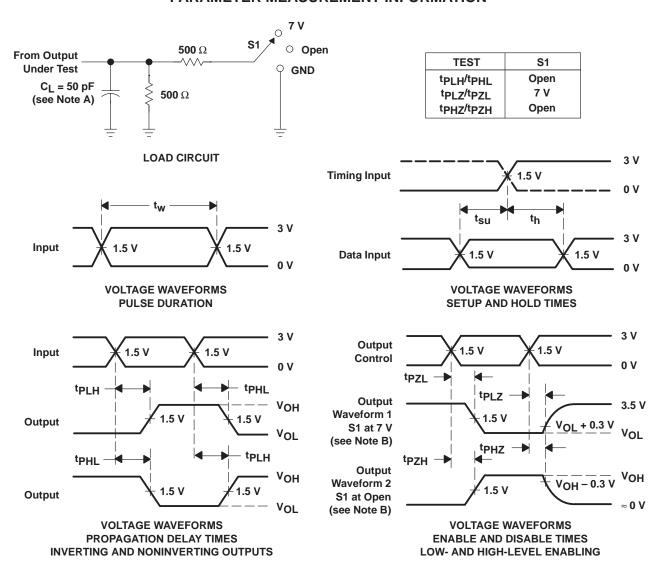
SN54ABT623A, SN74ABT623 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT623A		SN74ABT623		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	B B or A	1	2.6	4.1	1	4	1	4.6	ns
^t PHL			1	2.6	4.2	0.8	4.1	1	4.6	
^t PZH	OEBA	А	1.7	3.4	6.5	1.2	5.4	1.7	7.5	ns
t _{PZL}			1.7	3.8	6.5	1.5	6.8	1.7	7.5	
^t PHZ	OEBA	А	1.7	4.2	6.5	1.7	7.1	1.7	7.5	ns
t _{PLZ}			1.7	4.7	6.5	1.5	7.1	1.7	7.5	
^t PZH	OEAB	OEAB B	1.7	4.8	6.5	1.2	6.8	1.7	7.5	
t _{PZL}			1.7	4	6.5	1.7	6.5	1.7	7.5	ns
^t PHZ	OEAB	В	1.7	3.9	6.5	1.5	6.8	1.7	7.5	20
^t PLZ		D D	1.7	3.2	6.5	1.3	5.8	1.7	7.5	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \, \Omega$, $t_f \leq 2.5 \, \text{ns}$, $t_f \leq 2.5 \, \text{ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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